

CMLDM8002A
CMLDM8002AG*
CMLDM8002AJ

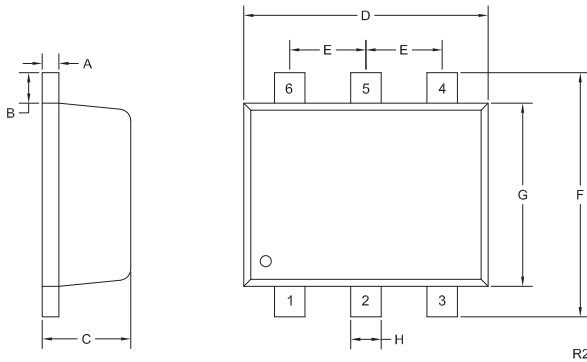
SURFACE MOUNT SILICON
DUAL P-CHANNEL
ENHANCEMENT-MODE
MOSFETS



ELECTRICAL CHARACTERISTICS PER TRANSISTOR - Continued: ($T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
$r_{DS(ON)}$	$V_{GS}=10V, I_D=500mA$			2.5	Ω
$r_{DS(ON)}$	$V_{GS}=10V, I_D=500mA, T_J=125^\circ\text{C}$			4.0	Ω
$r_{DS(ON)}$	$V_{GS}=5.0V, I_D=50mA$			3.0	Ω
$r_{DS(ON)}$	$V_{GS}=5.0V, I_D=50mA, T_J=125^\circ\text{C}$			5.0	Ω
g_{FS}	$V_{DS}=10V, I_D=200mA$	200			mS
C_{rss}	$V_{DS}=25V, V_{GS}=0, f=1.0MHz$			7.0	pF
C_{iss}	$V_{DS}=25V, V_{GS}=0, f=1.0MHz$			70	pF
C_{oss}	$V_{DS}=25V, V_{GS}=0, f=1.0MHz$			15	pF
$Q_{g(tot)}$	$V_{DS}=25V, V_{GS}=4.5V, I_D=100mA$		0.72		nC
Q_{gs}	$V_{DS}=25V, V_{GS}=4.5V, I_D=100mA$		0.25		nC
Q_{gd}	$V_{DS}=25V, V_{GS}=4.5V, I_D=100mA$		0.16		nC
t_{on}, t_{off}	$V_{DD}=30V, V_{GS}=10V, I_D=200mA$ $R_G=25\Omega, R_L=150\Omega$			20	ns

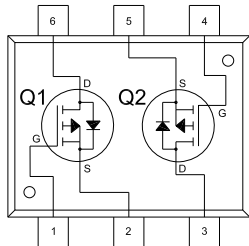
SOT-563 CASE - MECHANICAL OUTLINE



SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.0027	0.007	0.07	0.18
B		0.008		0.20
C	0.017	0.024	0.45	0.60
D	0.059	0.067	1.50	1.70
E		0.020		0.50
F	0.059	0.067	1.50	1.70
G	0.043	0.051	1.10	1.30
H	0.006	0.012	0.15	0.30

SOT-563 (REV: R2)

CMLDM8002A (USA Pinout)
CMLDM8002AG*



LEAD CODE:

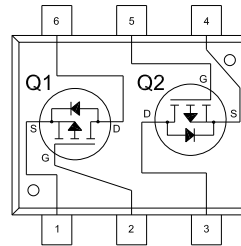
- 1) Gate Q1
- 2) Source Q1
- 3) Drain Q2
- 4) Gate Q2
- 5) Source Q2
- 6) Drain Q1

MARKING CODES:

CMLDM8002A: C08
CMLDM8002AG*: CG8

* Device is *Halogen Free* by design

CMLDM8002AJ (Japanese Pinout)



LEAD CODE:

- 1) Source Q1
- 2) Gate Q1
- 3) Drain Q2
- 4) Source Q2
- 5) Gate Q2
- 6) Drain Q1

MARKING CODE: CJ8

R7 (8-June 2015)

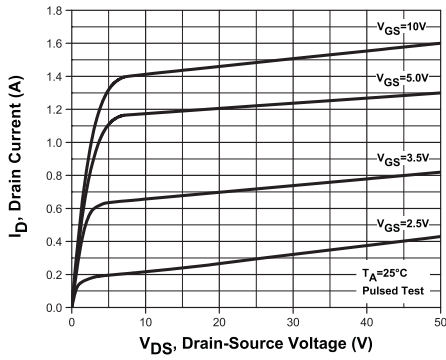
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SURFACE MOUNT SILICON
 DUAL P-CHANNEL
 ENHANCEMENT-MODE
 MOSFETS

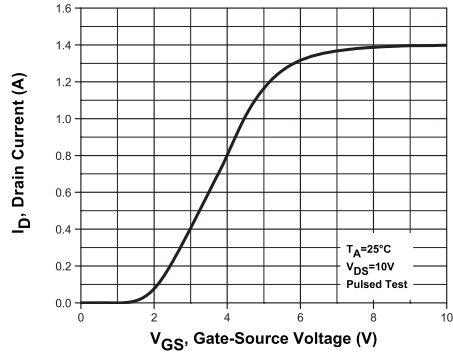


TYPICAL ELECTRICAL CHARACTERISTICS

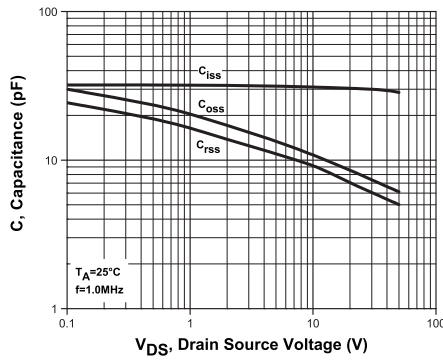
Output Characteristics



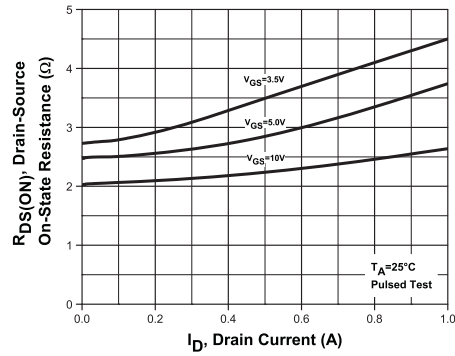
Transfer Characteristics



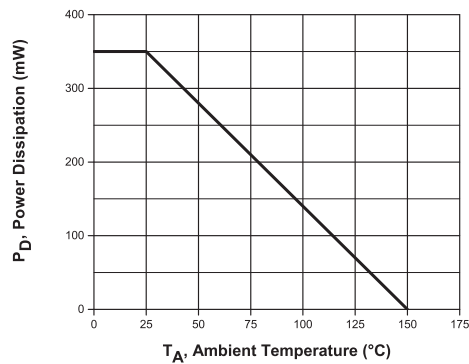
Capacitance



Drain Source On Resistance



Power Derating



R7 (8-June 2015)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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